



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-03-20
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	AHZH*TYU010M	A	BO2A	2015-03-20
Amount	UoM	Unit type	ECOPACK2/RoHS	
250.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SMC	6.69,5.63,2.38	1	J bend	
Comment	Package: SMC CLIP (SOD 15); MDF valid for SM30T10AY			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name		AHZH*TYU010M					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
die (s)	Other inorganic materials	9.365	mg	supplier	die	Silicon (Si)	7440-21-3		9.059	mg	967325	36236	
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.052	mg	5553	208	
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	854	32	
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.013	mg	1388	52	
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.038	mg	4058	152	
die (s)				supplier	metallization	Gold (Au)	7440-57-5		0.038	mg	4058	152	
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.052	mg	5553	208	
die (s)				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.035	mg	3737	140	
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	1281	48	
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.058	mg	6193	232	
Leadframe	Copper & its alloys	104.74	mg	supplier	alloy	Copper (Cu)	7440-50-8		103.836	mg	991369	415344	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.104	mg	993	416	
Leadframe				supplier	alloy	Iron Phosphide (FeP)	25508-33-8		0.031	mg	296	124	
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.769	mg	7342	3076	
Soft solder	Other inorganic materials	4.277	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	3.999	mg	935001	15996	
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.064	mg	14964	256	
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.214	mg	50035	856	
Frame clip	Other inorganic materials	39.514	mg	supplier	clip	Copper (Cu)	7440-50-8		39.513	mg	1000000	158052	
encapsulation	Other inorganic materials	91.364	mg	supplier	mold compound	Silica, vitreous	60676-86-0		69.436	mg	759993	277744	
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		5.482	mg	60002	21928	
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.731	mg	8001	2924	
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		9.319	mg	101999	37276	
encapsulation				supplier	mold compound	Metal hydroxide	Proprietary		1.828	mg	20008	7312	
encapsulation				supplier	mold compound	Others	Proprietary		4.568	mg	49998	18272	
connections coating	Solder	0.741	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.741	mg	1000000	2964	